EFUG Workshop – Programme

EFUG Workshop, Part 1 –Tuesday, 20 September 2016 – 15:10-16:50, Room: Fraunhofer

15:10-15:30 **Ga contamination in silicon by focused ion beam milling: Atom Probe Tomography and simulation with dynamic model**
Jin Huang, TU Dresden

15:30-15:50 **Micro mechanical robustness tests of 28nm BEOL layer stack**
Eckhard Langer, Globalfoundries

15:50-16:10 **Laser based sample preparation for advanced packaging applications**
Thomas Höche, Fraunhofer IMWS

16:10-16:30 **Planar FIB Milling of Copper by using the Novel Rocking Stage Technology**
Sharang Sharang, TESCAN ORSAY HOLDING a.s.

16:30-16:50 **Fast, Reliable, Intuitive TEM Sample Preparation using a Load-Lockable Platform Combined with Smart Control Software**
Stephan Kleindiek, Kleindiek Nanotechnik GmbH

EFUG Workshop, Part 2 –Tuesday, 20 September 2016 – 17:10-18:10, Room: Fraunhofer

17:10-17:30 **Imaging and Analysis Solutions for 3D Devices**
Ingo Schulmeyer, Carl Zeiss Microscopy

17:30-17:50 **Innovative TEM sample Preparation on Helios G4 platform**
Trevan Landin, FEI

17:50-18:10 **FIB and P-FIB assisted sample preparation for in-situ TEM characterization**
Remy Berthier, CEA-LETI